

# TLC116 ---> TLC386 T/D/S/A

## SENSITIVE GATE TRIACS

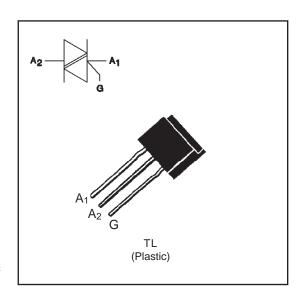
## **FEATURES**

- VERY LOW I<sub>GT</sub> = 5mA max
- LOW I<sub>H</sub> = 15mA max

## **DESCRIPTION**

The TLC116 ---> TLC386 T/D/S/A triac family uses a high performance glass passivated PNPN technology.

These parts are suitable for general purpose applications where gate high sensitivity is required. Application on 4Q such as phase control and static



## **ABSOLUTE RATINGS** (limiting values)

Symbol	Parameter				,	Unit		
IT(RMS) RMS on-state current				С	3		Α	
	(360° conduction angle)		Ta = 25°C		1.			
ITSM	Non repetitive surge peak on-state current ( Tj initial = 25°C )			tp = 8.3 ms			31.5	
				tp = 10 ms			30	
I <sup>2</sup> t	$I^2t$ value $tp = 10 \text{ ms}$				ns		A <sup>2</sup> s	
dl/dt	Critical rate of rise of on-state current Repetitiv Gate supply : $I_G = 50 \text{mA}$ dig/dt = 0.1A/ $\mu$ s						A/μs	
	N Rep							
Tstg Tj	Storage and operating junction temperature range - 40 to + 150 - 40 to + 110					°C		
TI	Maximum lead temperature for soldering during 4 s at 4.5 mm 230 from case					°C		
Symbol	Parameter	TLC					Unit	
		116 T/D/S/A	226	T/D/S/A	336	6 T/D/S/A	386 T/D/S/A	
VDRM VRRM	Repetitive peak off-state voltage Tj = 110°C	200		400		600	700	V

(1) With Cu surface 1cm<sup>2</sup>.

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## THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
Rth (j-a)	Junction to ambient on printed circuit with Cu surface 1cm <sup>2</sup>	50	°C/W
Rth (j-l) DC	Junction leads for DC	20	°C/W
Rth (j-l) AC	Junction leads for 360° conduction angle (F= 50 Hz)	15	°C/W

## **GATE CHARACTERISTICS** (maximum values)

 $P_{G}$  (AV) = 0.1W  $P_{GM}$  = 2W (tp = 20  $\mu$ s)  $I_{GM}$  = 1A (tp = 20  $\mu$ s)  $V_{GM}$  = 16V (tp = 20  $\mu$ s).

## **ELECTRICAL CHARACTERISTICS**

Symbol	Test Conditions		Quadrant		Suffix			Unit	
					Т	D	S	Α	
IGT	$V_D=12V$ (DC) $R_L=33\Omega$	Tj=25°C	1-11-111	MAX	5	5	10	10	mA
			IV	MAX	5	10	10	25	
VGT	$V_D=12V$ (DC) $R_L=33\Omega$	Tj=25°C	I-II-III-IV	MAX		1	.5		V
VGD	VD=VDRM RL=3.3kΩ	Tj=110°C	I-II-III-IV	MIN	0.2		V		
tgt	$V_D=V_{DRM}$ $I_G=40$ mA $I_{G}/dt=0.5$ A/ $\mu$ s	Tj=25°C	I-II-III-IV	TYP	2		μs		
IL	IG= 1.2 IGT	Tj=25°C	I-III-IV	MAX	15	15	25	25	mA
			II		15	15	25	25	
IH *	I <sub>T</sub> = 100mA gate open	Tj=25°C		MAX	15	15	25	25	mA
V <sub>TM</sub> *	I <sub>TM</sub> = 4A tp= 380μs	Tj=25°C		MAX	1.85		V		
IDRM	V <sub>DRM</sub> Rated	Tj=25°C		MAX	AX 0.01			mA	
IRRM	IRRM VRRM Rated			MAX	0.75				
dV/dt *	Linear slope up to VD=67%VDRM gate open	Tj=110°C		TYP	10	10	20	20	V/µs
(dV/dt)c *	(dl/dt)c = 1.3A/ms	Tj=110°C		TYP	1	1	5	5	V/μs

<sup>\*</sup> For either polarity of electrode  $A_2$  voltage with reference to electrode  $A_1$ .

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## **ORDERING INFORMATION**

Package	IT(RMS)	V <sub>DRM</sub> / V <sub>RRM</sub>	Sensitivity Specification			
	Α	V	Т	D	s	Α
TLC6	3	200	Х	Х	Х	Х
		400	X	Х	Х	Х
		600	X	Х	Х	Х
		700	Х	Х	Х	Х

Fig.1: Maximum RMS power dissipation versus RMS on-state current (F=50Hz).

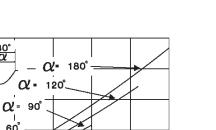
(Curves are cut off by (dl/dt)c limitation)

Q - 60°

**α** 30°

P (W)

0



IT(RMS)(A)

2.5

Fig.2: Correlation between maximum RMS power dissipation and maximum allowable temperatures (Tamb and Tlead).

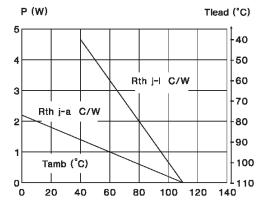


Fig.3: RMS on-state current versus case temperature.

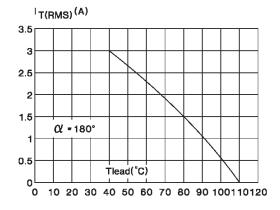
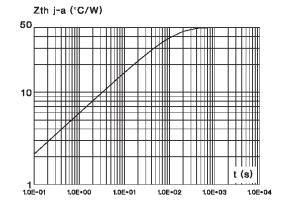
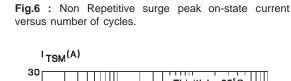


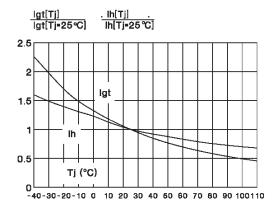
Fig.4: Thermal transient impedance junction to case and junction to ambient versus pulse duration.



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**Fig.5**: Relative variation of gate trigger current and holding current versus junction temperature.





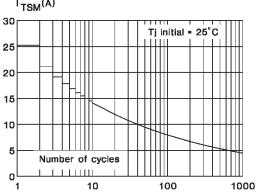
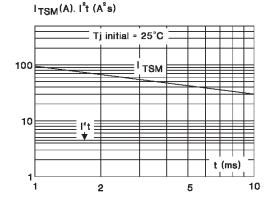
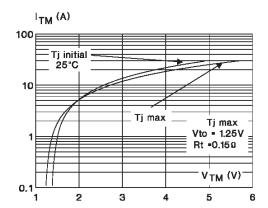


Fig.7 : Non repetitive surge peak on-state current for a sinusoidal pulse with width : t  $\leq$  10ms, and corresponding value of I²t.

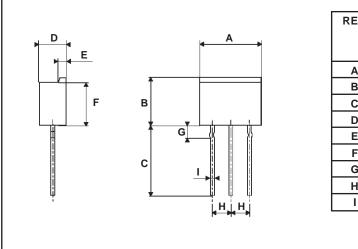
Fig.8 : On-state characteristics (maximum values).





## **PACKAGE MECHANICAL DATA**

## TL Plastic



REF.	DIMENSIONS						
	Millin	neters	Inches				
	Min.	Max.	Min.	Max.			
Α	9.55	10.05	0.375	0.396			
В	7.55	8.05	0.297	0.317			
C	12.70		0.500				
D	<b>D</b> 4.25 4.75		0.167	0.187			
Е	1.25	1.75	0.049	0.069			
F	6.75	7.25	0.266	0.285			
G		4.50		0.177			
Н	2.04 3.04		0.80	0.120			
I	0.75	0.85	0.029	0.033			

Marking: type number Weight: 0.75 g

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